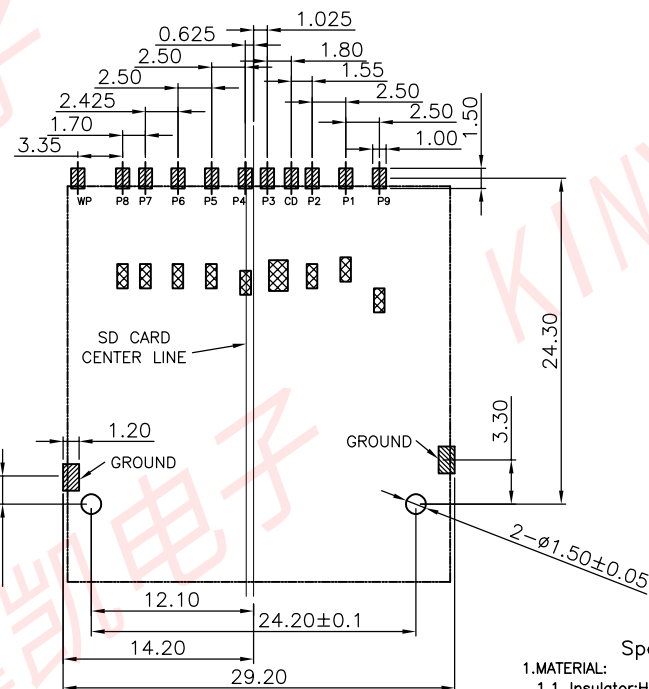
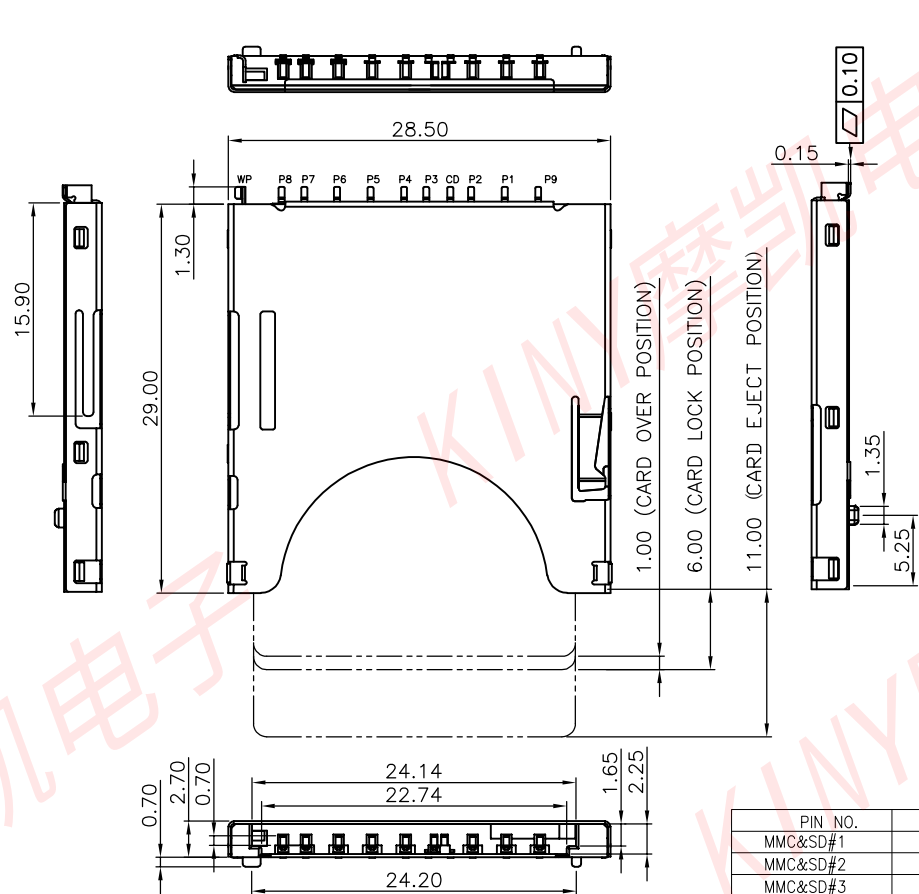


* 所有原料材质, 生产制程, 电镀必须符合HTR要求

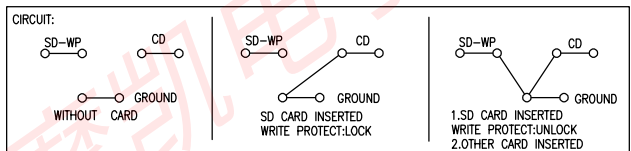


Pad Area
Keep Out Area
PCB LAYOUT TOP VIEW

PIN NO.	MEMORY CARD PIN NO.
MMC&SD#1	MMC&SD#1 (CD/DAT3)
MMC&SD#2	MMC&SD#2 (CMD)
MMC&SD#3	MMC&SD#3 (VSS1)
MMC&SD#4	MMC&SD#4 (VDD)
MMC&SD#5	MMC&SD#5 (CLK)
MMC&SD#6	MMC&SD#6 (VSS2)
MMC&SD#7	MMC&SD#7 (DAT0)
SD#8	SD-8 (DAT1)
SD#9	SD-9 (DAT2)

Specification

- MATERIAL:
 - Insulator: High Temperature Thermoplastic, (LCP E130I), UL Black 94V-0.
 - Contact: Phosphor Bronze (C5191-EH, T=0.15±0.03mm)
 - Shell: SUS301-3/4H T=0.20±0.01mm
- Plating:
 - Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 80u"min Sn over Ni on solder area
 - Shell: Plated 50u"min Ni Overall
- Electrical:
 - Current Rating :0.5A AC/DC max.
 - Voltage Rating :12V AC/DC
 - Ambient Temperature Range : -20°C~+60°C
 - Storage Temperature Range : -40°C~+70°C
 - Ambient Humidity Range :95% R.H. Max.
 - Contact Resistance:100mΩ max.
 - Insulation Resistance:1000MΩ min./500VDC
 - Mating Cycles:5,000 Insertions
- Usable Memory Card: SD&MMC Card



REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
A		NEW RELEASE	Janyz	2018.08.01

KINYY		东莞市摩凯电子有限公司			
DIMENSIONS INIT: mm		PRODUCT NAME :	SD Push Push	DRAWING:	Janyz
UNLESS OTHERWISE SPECIFIABLE		PRODUCT NO. :	SDP-T1250-1B-W	CHECK:	Alex
DIMENSION TOLERANCE		DRAWING NO. :	D-SDP-T1250-1B-W	APPROVED:	Alex
X.X: ± 0.35				SCALE:	1:1
X.XX: ± 0.20				DWG ID:	C D
X.XXX: ± 0.10				REV.:	A
ANGULAR: ± 2°				PAGE:	1 of 1